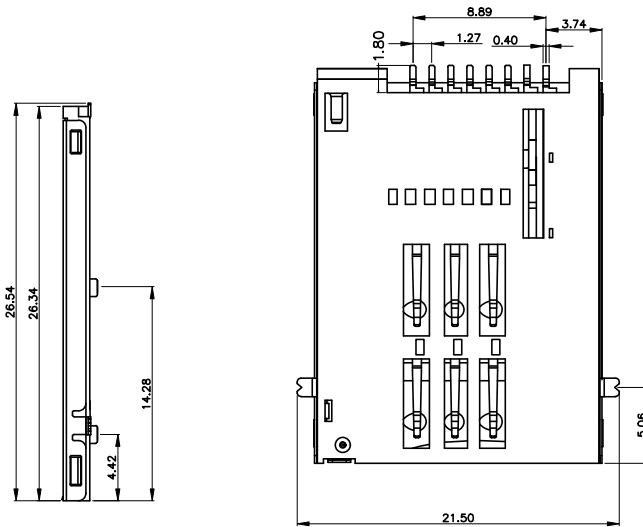
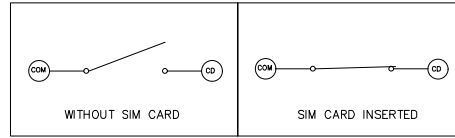
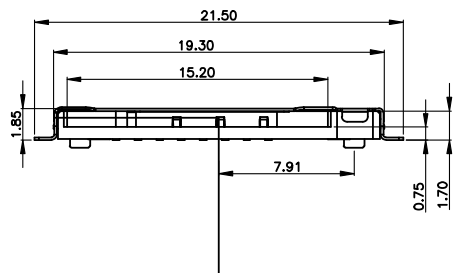
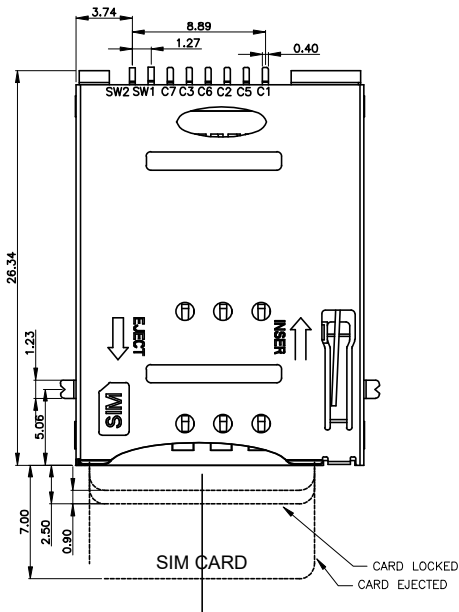
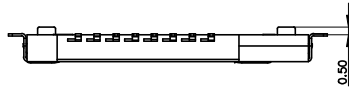




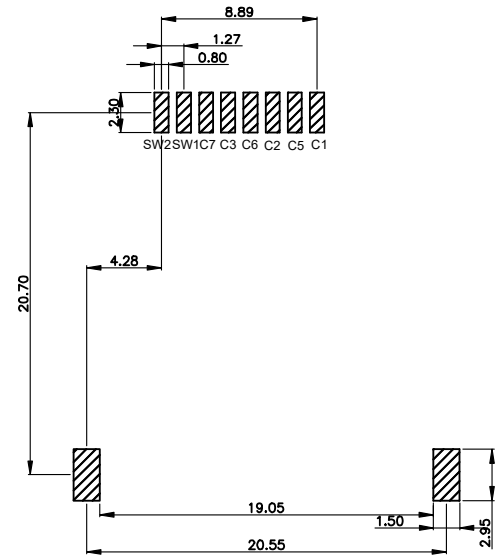
SIM pin assignment	
PIN#	Name
C1	VCC 电压
C2	RST 重置
C3	CLK 时钟
C5	GND 接地
C6	VPP 电压
C7	I/O 输入输出

REV.	ECN NO OR DESCRIPTION	REVISED	DATE

MATERIAL: Specification
Insulator: High Temperature Thermoplastic,
UL 94V-0. COLOR"BLACK LCP
(颜色: 黑色_CP, 最大厚度JUL 94V-0)
Contact: Copper Alloy

PLATING:
Contact: Plated 50u" Ni Overall
Plated Au Selective Contact Area
Plated 100u" Sn Over Ni On Solder Area
(接触端子镀: 金厚度50U, 镀层厚度1U, 焊盘镀50U/秒)
Shell: Plated 50u" Ni Overall
Plated 1u"Au Selective Contact Area
(壳体镀: 金50U, 焊盘1U)

Electrical:
Current Rating :0.5Amps max(额定电流:0.5A最大)
Voltage Rating :5V AC/DC(额定电压:5V AC/DC)
Ambient Temperature Range :-20°C~+60°C(环境温度: -20度~+60度)
Storage Temperature Range :-40°C~+70°C(存储温度: -40度~+80度)
Ambient Humidity Range :95% R.H. Max.(相对湿度: 95%最大)
Contact Resistance:100m max.(接触电阻: 100毫欧 最大)
Insulation Resistance:1000M min./500VDC(绝缘电阻: 100兆欧最小)
Mating Cycles:5,000 Insertions(插拔: 5000次)
寿命: 260°C



PCB 焊盘区
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

UNLESS OTHERWISE SPECIFIED TOLERANCES		 东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD				
DECIMALS: ANGLES:		TITLE Mini Sim Card Push Push 6+2P Smt无铅				
X :±0.5 X :±2°	DWN xiong SIM-208					
X.X :±0.20 X.X :±1°	CHKD lee		SCALE:1:1		UNIT: mm 	
X.XX :±0.10	APVD wang		SIZE: A4	SHEET:10F 1	REV: A4	
		CUSTOMER COPY				